



# EPO-TEK® T6067-3

Technical Data Sheet

For Reference Only

Thermally Conductive Epoxy

Date:	May 2023
Rev:	XVI
No. of Components:	Single
Mix Ratio by Weight:	N/A
Specific Gravity:	1.80
Pot Life:	28 Days
Shelf Life- Bulk:	One year at -40°C
Shelf Life- Syringe:	One year at -40°C

## Recommended Cure: 150°C / 1 Hour

### Minimum Alternative Cure(s):

*May not achieve performance properties listed below*  
125°C / 2 Hours

### NOTES:

- Container(s) should be kept closed when not in use.
- Filled systems should be stirred thoroughly before mixing and prior to use.
- Performance properties (rheology, conductivity, others) of the product may vary from those stated on the data sheet when bi-pak/syringe packaging or post-processing of any kind is performed. Epoxy's warranties shall not apply to any products that have been reprocessed or repackaged from Epoxy's delivered status/container into any other containers of any kind, including but not limited to syringes, bi-paks, cartridges, pouches, tubes, capsules, films or other packages.

**Product Description:** EPO-TEK® T6067-3 is a single component thermally conductive epoxy for hybrid die and component attach. It can also be used for semiconductor and high temperature ceramic and vacuum packaging. It is a lower viscosity version of EPO-TEK® T6067.

**Typical Properties:** Cure condition: 150°C / 1 Hour      Different batches, conditions & applications yield differing results.  
Data below is not guaranteed. To be used as a guide only, not as a specification. \* denotes test on lot acceptance basis

### PHYSICAL PROPERTIES:

* Color (before cure):	White		
* Consistency:	Smooth thixotropic paste		
* Viscosity (23°C) @ 1 rpm:	100,000-150,000 cPs		
Thixotropic Index:	1.6		
* Glass Transition Temp:	≥ 90 °C (Dynamic Cure: 20-300°C/ISO 25 Min; Ramp -10-200°C @20°C/Min)		
Coefficient of Thermal Expansion (CTE):			
Below Tg:	47	× 10 <sup>-6</sup> in/in°C	
Above Tg:	167	× 10 <sup>-6</sup> in/in°C	
Shore D Hardness:	89		
Lap Shear @ 23°C:	> 2,000 psi		
Die Shear @ 23°C:	≥ 25 Kg 8,890 psi		
Degradation Temp:	403 °C		
Weight Loss:			
@ 200°C:	0.06	%	
@ 250°C:	0.44	%	
@ 300°C:	0.90	%	
Suggested Operating Temperature:	< 300 °C (Intermittent)		
Storage Modulus:	495,349 psi		
Ion Content:	Cl <sup>-</sup> :	195 ppm	Na <sup>+</sup> : 7 ppm
	NH <sub>4</sub> <sup>+</sup> :	70 ppm	K <sup>+</sup> : 14 ppm
* Particle Size:	≤ 60 microns		

### ELECTRICAL AND THERMAL PROPERTIES:

Thermal Conductivity:	1.0	W/mK
Volume Resistivity @ 23°C:	≥ 2 × 10 <sup>13</sup>	Ohm-cm
Dielectric Constant (1KHz):	3.33	
Dissipation Factor (1KHz):	0.011	

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## EPO-TEK® T6067-3 Advantages & Suggested Application Notes:

- A high viscosity and thixotropic paste suitable for dispensing, screen printing or manual hand application.
- Performs exceptionally well as a die-attach for small chips such as GaAs, LEDs, diodes and SMD components.
- Capable of resisting 260° C reflow processes, low outgassing hermetic lid seal processes, and organic burn-in up to 150° C/1000 hour storage.
- Capable of JEDEC Level II die attach packaging on die paddles and lead frames.
- Popular for non-electrically conductive die attach capable of bonding to a wide range of substrates including kovar ceramic and BT.
- Available in a higher viscosity version; T6067.
- Can be used as a non-conductive stacking epoxy, in conjunction with E3037, for attaching SMD in hybrid and other packages.

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